## LCD / LCM SPECIFICATION



WINSTAR Display Co.,Ltd. 華凌光電股份有限公司





## Winstar Display Co., LTD 華凌光電股份有限公司



### **SPECIFICATION**

CUSTOMER :	~ ~ ~ ~ ~ ~ ~
MODULE NO.:	WG12864M-TMI-V#N

ΛDE	DO	<b>VED</b>	$\mathbf{pv}$
$\mathbf{AII}$		'V LJ	DI.

(FOR CUSTOMER USE ONLY)

PCB VERSION:

DATA:

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

VERSION	DATE	REVISED	SUMMARY		
		PAGE NO.			
D	2017/02/24	Modify		Backlight	
	20170421		Information		



# Winstar Display Co., LTD

華凌光電股份有限公司

MODLE NO:

### **RECORDS OF REVISION**

DOC. FIRST ISSUE

VERSION	DATE	REVISED PAGE NO.	SUMMARY
0	2009/03/20		First issue
Α	2013/10/14		Remove IC information
			Modify B/L information
В	2016/01/27		Modify Precautions in use
			of LCD Modules
			& Static electricity test
С	2016/04/20		Modify Response Time
D	2017/02/24		Modify Backlight
		Y	Information



### **Contents**

- 1. Module Classification Information
- 2. Precautions in use of LCD Modules
- 3.General Specification
- 4. Absolute Maximum Ratings
- **5. Electrical Characteristics**
- 6. Optical Characteristics
- 7.Interface Pin Function
- 8. Contour Drawing & Block Diagram
- 9.Reliability
- 10.Backlight Information
- 11.Inspection specification
- 12. Material List of Components for RoHs
- 13. Recommendable Storage



### 1. Module Classification Information

① Brand: WINSTAR DISPLAY CORPORATION

② Display Type :  $H \rightarrow Character Type$ ,  $G \rightarrow Graphic Type$  ,  $X \rightarrow TAB Type$ ,  $O \rightarrow COG Type$ 

③ Display Font: 128 \* 64 dot

4 Model serials no.

 $\bigcirc$  Backlight Type : N $\rightarrow$ Without backlight T $\rightarrow$ LED, White S $\rightarrow$ LED, High light White

 $B \rightarrow EL$ , Blue green  $A \rightarrow LED$ , Amber  $L \rightarrow LED$ , Full color  $D \rightarrow EL$ , Green  $R \rightarrow LED$ , Red  $J \rightarrow DIP$  LED, Blue  $W \rightarrow EL$ , White  $O \rightarrow LED$ , Orange  $K \rightarrow DIP$  LED, White

 $M\rightarrow EL$ , Yellow Green  $G\rightarrow LED$ , Green  $E\rightarrow DIP$  LED, Yellow Green

V→FSTN Negative, Blue

F $\rightarrow$ CCFL, White P $\rightarrow$ LED, Blue H $\rightarrow$ DIP LED, Amber Y $\rightarrow$ LED, Yellow Green X $\rightarrow$ LED, Dual color I $\rightarrow$ DIP LED, Red

 $G \rightarrow LED$ , Green  $C \rightarrow LED$ , Full color

⑥ LCD Mode: B→TN Positive, Gray

N→TN Negative, T→FSTN Negative, Black

L→VA Negative D→FSTN Negative (Double film)

 $H \rightarrow HTN$  Positive, Gray  $F \rightarrow FSTN$  Positive  $I \rightarrow HTN$  Negative, Black  $K \rightarrow FSC$  Negative  $U \rightarrow HTN$  Negative, Blue  $S \rightarrow FSC$  Positive

 $M \rightarrow STN$  Negative, Blue  $E \rightarrow ISTN$  Negative, Black  $G \rightarrow STN$  Positive, Gray  $C \rightarrow CSTN$  Negative, Black  $Y \rightarrow STN$  Positive, Yellow Green  $A \rightarrow ASTN$  Negative, Black

⑦ LCD Polarize Type/ A→Reflective, N.T, 6:00 H→Transflective, W.T,6:00

Temperature D→Reflective, N.T, 12:00 K $\rightarrow$ Transflective, W.T,12:00 range/ View G $\rightarrow$ Reflective, W. T, 6:00 C $\rightarrow$ Transmissive, N.T,6:00 direction J $\rightarrow$ Reflective, W. T, 12:00 F $\rightarrow$ Transmissive, N.T,12:00 B $\rightarrow$ Transflective, N.T,6:00 I $\rightarrow$ Transmissive, W. T, 6:00

E→Transflective, N.T.12:00 L→Transmissive, W.T,12:00

Special Code
V: Build in Negative Voltage

#: Fit in with the ROHS Directions and regulations

N: IC NT7107C,NT7108C



### 2. Precautions in use of LCD Modules

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8) Winstar have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9) Winstar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Winstar have the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.



## **3.General Specification**

Item	Dimension	Unit
Number of dots	128 x 64 dots	_
Module dimension	95.5x 50.2 x 13.6(MAX)	mm
View area	72.0 x 40.0	mm
Active area	66.52 x 33.24	mm
Dot size	0.48 x 0.48	mm
Dot pitch	0.52 x 0.52	mm
LCD type	STN Negative, Blue Transmissive (In LCD production, It will occur slightly color difficulty guarantee the same color in the same batc	
Duty	1/64	
View direction	6 o'clock	
Backlight Type	LED ,White	
IC	NT7107, NT7108	



## **4.Absolute Maximum Ratings**

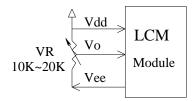
Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	$T_{\mathrm{OP}}$	-20	_	+70	$^{\circ}\!\mathbb{C}$
Storage Temperature	$T_{ST}$	-30	_	+80	$^{\circ}\!\mathbb{C}$
Supply Voltage For Logic	$V_{DD}$ - $V_{SS}$	-0.3	_	7.0	V
Driver Supply Voltage	$V_{ m LCD}$	V <sub>EE</sub> -0.3	_	V <sub>DD</sub> +0.3	V



### **5.Electrical Characteristics**

ITEM	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT
Supply Voltage For Logic	$V_{DD}$ - $V_{SS}$	_	4.5	5.0	5.5	V
Supply Voltage For		Ta=-20°C	_	_	10.6	V
LCD	$V_{DD}$ - $V_{O}$	Ta=25°℃	8.8	9.1	9.4	V'
*Note		Ta=70°C	8.4	_		V
Input High Volt.	$V_{\mathrm{IH}}$	_	$0.7~\mathrm{V_{DD}}$	_	$V_{ m DD}$	V
Input Low Volt.	$V_{IL}$	_	0		0.8	V
Output High Volt.	$V_{\mathrm{OH}}$	_	2.4		_	V
Output Low Volt.	$V_{\mathrm{OL}}$	_		<b>&gt;</b> -	0.4	V
Supply Current	$I_{\mathrm{DD}}$	V <sub>DD</sub> =5.0V	-	2.5	7.5	mA

<sup>\*</sup> Note: Please design the VOP adjustment circuit on customer's main board





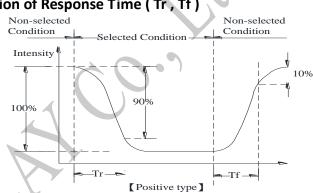
## **6.Optical Characteristics**

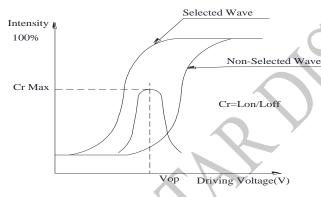
Item	Symbol	Condition	Min	Тур	Max	Unit
View Angle	θ	CR≧2	0	_	20	$\phi = 180^{\circ}$
	θ	CR≧2	0	_	40	$\phi = 0^{\circ}$
	θ	CR≧2	0	_	30	$\phi = 90^{\circ}$
	θ	CR≧2	0	_	30	$\phi = 270^{\circ}$
Contrast Ratio	CR	_	_	3	_	_
Response Time	T rise	_	_	200	300	ms
	T fall	_	_	250	350	ms

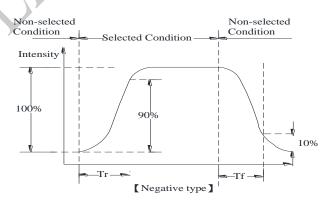
#### **Definition of Operation Voltage (Vop)**

### Selected Wave Intensity A 100% Non-Selected Wave Cr Max Cr=Lon/Loff Driving Voltage(V)

#### Definition of Response Time (Tr, Tf)







#### **Conditions:**

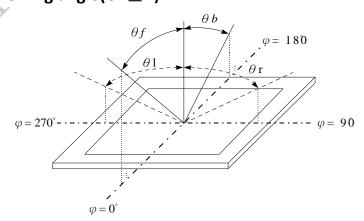
Operating Voltage: Vop

Viewing Angle( $\theta$ ,  $\varphi$ ):  $0^{\circ}$ ,  $0^{\circ}$ 

Frame Frequency: 64 HZ

Driving Waveform: 1/N duty, 1/a bias

#### **Definition of viewing angle(CR≥2)**



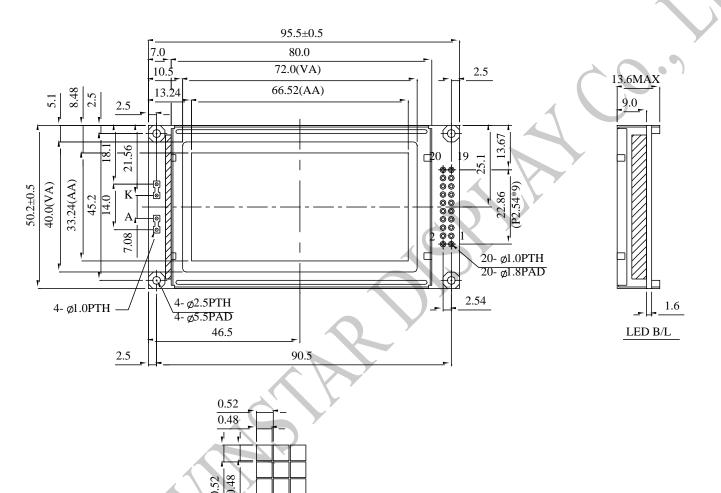


### **7.Interface Pin Function**

Pin No.	Symbol	Level	Description
1	$V_{SS}$	0V	GND
2	$V_{\mathrm{DD}}$	5.0V	Power Supply
3	Vo	(Variable)	Contrast Adjustment
4	D/I	H/L	Data /Instruction
5	R/W	H/L	Data Read/Write
6	Е	Н	H→L Enable signal
7	DB0	H/L	Data bus line
8	DB1	H/L	Data bus line
9	DB2	H/L	Data bus line
10	DB3	H/L	Data bus line
11	DB4	H/L	Data bus line
12	DB5	H/L	Data bus line
13	DB6	H/L	Data bus line
14	DB7	H/L	Data bus line
15	CS1	Н	Chip Select for IC1
16	CS2	Н	Chip Select for IC2
17	/RST	L	Reset
18	Vee	_	Negative Voltage output
19	A	_	LED+
20	K	_	LED-



### **8.Contour Drawing & Block Diagram**

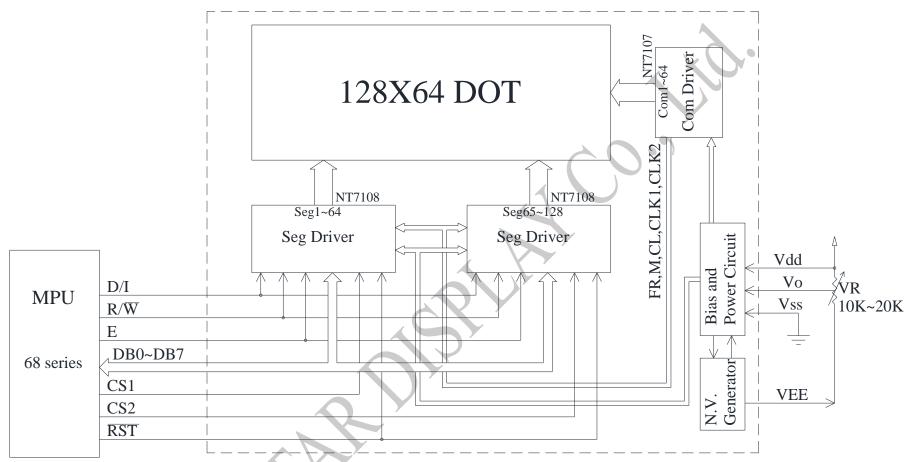


PIN NO.	SYMBOL
1	Vss
2	Vdd
3	Vo
4	D/I
5	R/W
6	Е
7	DB0
8	DB1
9	DB2
10	DB3
11	DB4
12	DB5
13	DB6
14	DB7
15	CS1
16	CS2
17	RST
18	VEE
19	A
20	K

The non-specified tolerance of dimension is  $\pm 0.3 \text{ mm}$ .

DOT SIZE SCALE 10/1





External contrast adjustment.



### 9.Reliability

Content of Reliability Test (Wide temperature, -20°C~70°C)

Environmental Test				
Test Item	Content of Test	Test Condition	Not e	
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2	
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2	
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs	_	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1	
High Temperature/ Humidity storage	The module should be allowed to stand at 60 °C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2	
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation  -20°C 25°C 70°C  30min 5min 30min 1 cycle	-20°C/70°C 10 cycles		
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3	
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact), ±800v(air), RS=330Ω CS=150pF 10 times		

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal

Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.



## **10.Backlight Information**

#### **Specification**

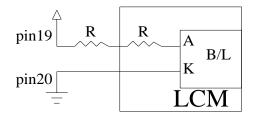
PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	20	64	80	mA	V=3.5V(Note 1)
Supply Voltage	v	3.4	3.5	3.6	V	- × O
Reverse Voltage	VR	_	_	5	V	-
Luminance (Without LCD)	IV	760	950	_	CD/M <sup>2</sup>	ILED=64mA
LED Life Time (For Reference only)	_	_	50K	- \	Hr.	ILED=64mA 25°C,50-60%RH, (Note 2)
Color	White			V Y		

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

Note 1: Supply current minimum value is only for reference since LED brightness efficiency keeps enhancing. Current consumption becomes less and less to achieve the same luminance.

Note 2:50K hours is only an estimate for reference.

Drive from pin19,pin20





## 11.Inspection specification

NO	Item	Criterion				AQL	
		Missing vertical, horizontal segment, segment contrast defect.					
		Missing character , dot or icon.					
		Display malfunction.					
01	Electrical	No function or no display.					
01	Testing	Current consumption exceeds product specifications.					
		LCD viewing ang	gle defect.		V.C		
		Mixed product types.					
		Contrast defect.					
	Dia ale an coleita	2.1 White and b	lack spots	on display $\leq$ 0.25	mm, no more than		
02	Black or white	three white or b	lack spots	present.	(00)	2.5	
02	spots on LCD	2.2 Densely spa	ced: No m	ore than two spots	s or lines within	2.5	
	(display only)	3mm					
		3.1 Round type	: As follow	ing drawing	Acceptable Q TY		
		Ф=( x + y ) / 2		Ф≦0.10	Accept no dense		
		_X_	1	0.10<Φ≦0.20	2		
		<b>-</b>	<b>V</b>	0.20<Φ≦0.25	1	2.5	
	LCD black	• .	Y	<del>0.25 &lt; Φ</del>	0		
	spots, white	0.23 👽					
03	spots,						
05	contaminatio	3.2 Line type : (/	As followir	ng drawing)			
	n		Length	Width	Acceptable Q TY		
	(non-display)	v <b>¥</b> w		W≦0.02	Accept no dense		
		→ +	L≦3.0	0.02 < W ≤ 0.03	·	2.5	
		L	L≦2.5	0.03 < W ≤ 0.05	2	2.5	
	4			0.05 < W	As round type		
		If bubbles are vi	sible,	Size Φ	Acceptable Q TY		
		judge using blac	k spot	Ф≦0.20	Accept no dense		
04	Polarizer	specifications, not easy		0.20<Φ≦0.50	3	2.5	
	bubbles	to find, must ch	eck in	0.50<Φ≦1.00	2		
		specify direction.		1.00 < Ф	0	1	
				Total Q TY	3		



NO	Item	Criterion					
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination					
		Symbols Define:					
		x: Chip length y:	Chip width z: Chip	thickness			
		k: Seal width t:	Glass thickness a: LCI	O side length			
		L: Electrode pad length	:				
		6.1 General glass chip:					
		6.1.1 Chip on panel sur	face and crack between	panels:	V		
			N. C.				
		z: Chip thickness	y: Chip width	x: Chip length			
06	Chipped	Z≦1/2t	Not over viewing area	x ≦ <b>1/</b> 8a	2.5		
	glass	1/2t < z ≦ 2t	Not exceed 1/3k	x≦1/8a	2.3		
		⊙ If there are 2 or mor 6.1.2 Corner crack:	e chips, x is total length	of each chip.			
		z: Chip thickness	y: Chip width	x: Chip length			
	Ny	Z≦1/2t	Not over viewing	x ≤ 1/8a			
		_= 4-0	area	400			
		1/2t < z ≤ 2t	Not exceed 1/3k	x ≤ 1/8a			
		⊙If there are 2 or mor	e chips, x is the total ler	ngth of each chip.			
<u> </u>		<u> </u>					



NO	Item	Criterion			AQL			
		Symbols :						
			nip width z: Chip th	nickness				
				ide length				
		L: Electrode pad length	_					
		6.2 Protrusion over termi						
		6.2.1 Chip on electrode pa	ad :	A				
			<b>T</b>	2				
				X V	<b>V</b>			
		War Al	Z					
		1/200						
		The state of the s	W.	2000				
			inarrosonax					
				:: Chip thickness				
			x≦1/8a	$0 < z \le t$				
		6.2.2 Non-conductive por	tion:	<b>Y</b>				
		l me L						
06	Glass				2.5			
	crack							
		V	Az v	A Z				
			K					
		X	34	X				
		y: Chip width	x: Chip length	z: Chip thickness				
		y≦ L	x ≦ 1/8a	$0 < z \leq t$				
		$\odot$ If the chipped area touches the ITO terminal, over 2/3 of the ITO must						
		remain and be inspected according to electrode terminal specifications.						
		⊙ If the product will be heat sealed by the customer, the alignment mark not						
		be damaged.						
	N	6.2.3 Substrate protubera	nce and internal crack.					
		1 Annual Control	y: width	x: length				
			y≦1/3L	$x \le a$				
		y y						
		389						



NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
		8.1 Illumination source flickers when lit.	0.65
	Backlight	8.2 Spots or scratched that appear when lit must be judged.	2.5
80	elements	Using LCD spot, lines and contamination standards.	
		8.3 Backlight doesn't light or color wrong.	0.65
		9.1 Bezel may not have rust, be deformed or have fingerprints,	2.5
09	Bezel	stains or other contamination.	
		9.2 Bezel must comply with job specifications.	0.65
		10.1 COB seal may not have pinholes larger than 0.2mm or	2.5
		contamination.	
		10.2 COB seal surface may not have pinholes through to the IC.	2.5
		10.3 The height of the COB should not exceed the height	0.65
		indicated in the assembly diagram.	
		10.4 There may not be more than 2mm of sealant outside the	2.5
		seal area on the PCB. And there should be no more than three	
		places.	
		10.5 No oxidation or contamination PCB terminals.	2.5
10	PCB · COB	10.6 Parts on PCB must be the same as on the production	0.65
10	TEB COB	characteristic chart. There should be no wrong parts, missing	
		parts or excess parts.	
		10.7 The jumper on the PCB should conform to the product	0.65
		characteristic chart.	
		10.8 If solder gets on bezel tab pads, LED pad, zebra pad or	2.5
		screw hold pad, make sure it is smoothed down.	
		10.9 The Scraping testing standard for Copper Coating of PCB	2.5
	46		
		X V	
		X * Y<=2mm <sup>2</sup>	
		11.1 No un-melted solder paste may be present on the PCB.	2.5
		11.2 No cold solder joints, missing solder connections,	2.5
11	Soldering	oxidation or icicle.	
		11.3 No residue or solder balls on PCB.	2.5
		11.4 No short circuits in components on PCB.	0.65



NO	Item	Criterion	AQL
		12.1 No oxidation, contamination, curves or, bends on interface	2.5
		Pin (OLB) of TCP.	
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface	2.5
		pin must be present or look as if it cause the interface pin to	
		sever.	2.5
	General	12.6 The residual rosin or tin oil of soldering (component or chip	
12		component) is not burned into brown or black color.	2.5
	appearance	12.7 Sealant on top of the ITO circuit has not hardened.	0.65
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging	
		specification sheet.	0.65
		12.11 Product dimension and structure must conform to product	
		specification sheet.	0.65
		12.12 Visual defect outside of VA is not considered to be	
		rejection.	



### 12.Material List of Components for

### **RoHs**

1. WINSTAR Display Co., Ltd hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.						

- 2.Process for RoHS requirement: (only for RoHS inspection)
  - (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
  - (2) Heat-resistance temp. :

Reflow: 250°C,30 seconds Max.;

Connector soldering wave or hand soldering: 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5°C;

Recommended customer's soldering temp. of connector: 280°C, 3 seconds.



### 13. Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.





DACHE		www.dachs.es
winstar <u>LCM Sampl</u>	e Estimate Fe	edback Sheet
Nodule Number:		Page: 1
1 · Panel Specification:		
1. Panel Type:	Pass	☐ NG ,
2. View Direction:	Pass	☐ NG ,
3. Numbers of Dots:	Pass	☐ NG ,
4. View Area:	Pass	☐ NG ,
5. Active Area:	Pass	□ NG ,
6. Operating Temperature:	Pass	□ NG ,
7. Storage Temperature:	Pass	□ NG ,
8. Others:		
2 · Mechanical Specification:		<i>y</i>
1. PCB Size:	Pass	□ NG ,
2. Frame Size:	Pass	□ NG ,
3. Materal of Frame:	Pass	□ NG,
4. Connector Position:	Pass	□ NG ,
5. Fix Hole Position:	Pass	□ NG ,
6. Backlight Position:	☐ Pass	□ NG ,
7. Thickness of PCB:	☐ Pass	☐ NG ,
8. Height of Frame to PCB:	☐ Pass	□ NG ,
9. Height of Module:	Pass	□ NG ,
10. Others:	Pass	□ NG ,
3 · Relative Hole Size :		
1. Pitch of Connector:	☐ Pass	☐ NG ,
2. Hole size of Connector:	Pass	☐ NG ,
3. Mounting Hole size:	Pass	☐ NG ,
4. Mounting Hole Type:	Pass	☐ NG ,
5. Others:	Pass	☐ NG ,
4 · Backlight Specification :		
1. B/L Type:	Pass	☐ NG ,
2. B/L Color:	Pass	□ NG ,
3. B/L Driving Voltage (Refere	ence for LED Typ	
4. B/L Driving Current:	Pass	☐ NG ,
5. Brightness of B/L:	Pass	□ NG ,
6 B/I Solder Method:	Pass	□ NG

 $>>\,$  Go to page 2  $\,<<\,$ 

Pass NG,\_\_\_\_

7. Others:



	wins	tar

le Number:		Page: 2
Electronic Characteristics of M	<u>lodule</u> :	
Input Voltage:	Pass	☐ NG ,
Supply Current:	Pass	☐ NG ,
Driving Voltage for LCD:	Pass	☐ NG ,
Contrast for LCD:	Pass	☐ NG ,
B/L Driving Method:	Pass	☐ NG ,
Negative Voltage Output:	Pass	☐ NG ,
Interface Function:	Pass	☐ NG ,
LCD Uniformity:	Pass	☐ NG ,
ESD test:	Pass	☐ NG ,
Others:	Pass	☐ NG ,
Summary:		
	Input Voltage : Supply Current : Driving Voltage for LCD : Contrast for LCD : B/L Driving Method : Negative Voltage Output : Interface Function : LCD Uniformity : ESD test : Others : Summary :	Electronic Characteristics of Module:  Input Voltage: